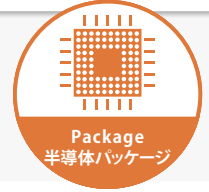


### Low-temperature curing Secondary mounting Underfill materials 低温硬化性二次実装アンダーフィル材



#### Applications 用途

Mount reinforcement of semiconductor packages and electronic parts for Automotive camera modules, Millimeter-wave radar modules, ECU, etc.  
車載カメラモジュール、車載ミリ波レーダー用モジュール、車載 ECU などへの半導体パッケージや電子部品の実装補強



Cures at low temperatures and can be applied for mount-reinforcement of precision parts that need to be protected from high temperatures. Improves the mounting reliability of automotive parts, for which high bonding strength is required.  
低温で硬化し高温を嫌う精密部品の実装に対応、接合強度が求められる車載部品の実装信頼性に貢献

Cures at a low temp of 80°C  
After curing, Tg is 140°C or greater  
80°Cで低温硬化、硬化物Tgは140°C以上

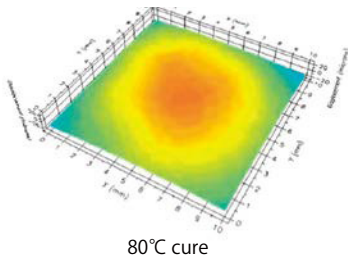
Smaller difference in heat shrinkage  
with other part, by high Tg  
高いTgにより低い熱収縮を実現

Possible to capillary flow up to 40mm  
in the gap of 20 μm  
20 μmの狭ギャップに最大40mm浸入可

#### Moire data at Room temperature 室温反り測定データ(シャドウモアレ)

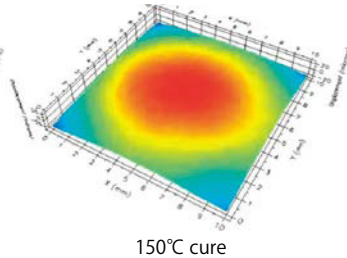
New Product

23 μm



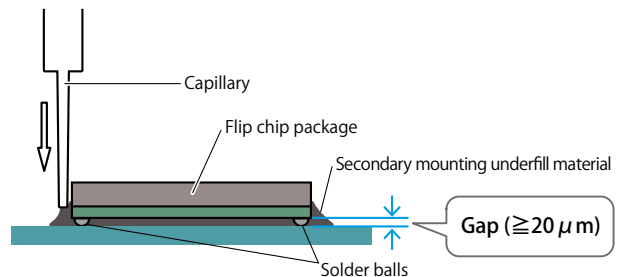
Conventional

66 μm

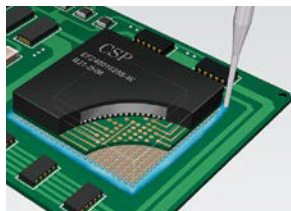


#### Suitable for mounting in areas with small gaps 狭ギャップに対応

Cross Section of a Circuited Board Being Mounted



#### Correspond to temperature cycle test under Automotive environment 車載環境下の温度サイクル試験にも対応



Item	New Product CV5350AS	Conventional
Temperature cycling test (TCT) -55°C ⇄ 125°C	1000 cycles Pass	300 cycles Pass

We also have "Corner reinforce type" suitable for partial reinforcement  
部分補強に適した「コーナー補強タイプ」も所有

#### General properties 一般特性

Item	Unit	CV5350AS
Minimum flow gap	μm	20
Viscosity (25°C)	mPa·s	4000
Glass transition temperature (Tg)	°C	150
C.T.E.1	ppm/°C	30
Elastic modulus (25°C)	GPa	10
Potential for reworking	—	Not possible

The above data are typical values and not guaranteed values. 上記データは当社測定による代表値であり、保証値ではありません。